

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chih-Yuan YU</td> <td>05/21/2006</td> </tr> <tr> <td>Ren-Chyi YOU</td> <td>05/21/2006</td> </tr> <tr> <td>Ming WANG</td> <td>05/21/2006</td> </tr> </tbody> </table>		Name	Execution Date	Chih-Yuan YU	05/21/2006	Ren-Chyi YOU	05/21/2006	Ming WANG	05/21/2006
Name	Execution Date								
Chih-Yuan YU	05/21/2006								
Ren-Chyi YOU	05/21/2006								
Ming WANG	05/21/2006								
RECEIVING PARTY DATA									
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.								
Street Address:	No. 8, Li-Hsin Road 6								
Internal Address:	Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11458554</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11458554				
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CORRESPONDENCE DATA									
Fax Number:	(214)200-0853								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	Brandi Sarfatis								
Total Attachments: 2 source=748Assignment#page1.tif									

CH \$40.00 11458554

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|--------------|----|--|
| (1) | Chih-Yuan YU | of | No. 364, Kung Ming Street, Yuan Lin Jr.
Chang Hua County, Taiwan, R.O.C. |
| (2) | Ren-Chyi YOU | of | No. 15, Alley 4, Lane 3, Rixin Road
Dongshan Shiang, Yilan County 269, Taiwan, R.O.C. |
| (3) | Ming WANG | of | 3F, No. 12, Lane 306, Minde Road
Zhonghe City, Taipei County 235, Taiwan, R.O.C. |

have invented certain improvements in

**INTEGRATED TRANSPORTATION CONTROL FOR
WAFER FABRICATION FACILITY**

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 X filed on July 19, 2006 and assigned application number 11/458554; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2005-0820 / 24061.748
Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chih-Yuan YU
Residence Address: No. 364, Kung Ming Street, Yuan Lin Jr.
Chang Hua County, Taiwan, R.O.C.

Dated: 2006/05/21 Chih-Yuan YU
Inventor Signature

Inventor Name: Ren-Chyi YOU
Residence Address: No. 15, Alley 4, Lane 3, Rixin Road
Dongshan Shiang, Yilan County 269, Taiwan, R.O.C.

Dated: 2006/05/21 Ren-Chyi You
Inventor Signature

Inventor Name: Ming WANG
Residence Address: 3F, No. 12, Lane 306, Minde Road
Zhonghe City, Taipei County 235, Taiwan, R.O.C.

Dated: 2006/05/21 Ming Wang
Inventor Signature